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HDP User Group Announces 21st Year of Operation

Cave Creek, Arizona January 13, 2014. The High Density Packaging (HDP) User Group International, headquartered in the United States, announces that it has begun its 21st year of service to members. The organization was founded in 1993 and has been in continuous operation since then.

The foundation of HDP User Group is multi-company cooperation on technical issues of common concern to its members such as characterization of new packaging concepts with respect to reliability and technical performance. Area array packaging using BGA packages was the first packaging concept addressed 20 years ago. Concepts such as Chip Scale Packaging (CSP) and Wafer Scale-CSP were addressed soon thereafter. Members contribute the resources needed for running the projects and share results. This achieves high degrees of leverage on their resources and accomplishes much more with much less from each Member. Shrinking R&D budgets and distributed global manufacturing have made the HDP User Group model even more applicable now than it was 20 years ago.

Today the organization is mature with 45 members, and a broad project portfolio.

The Group currently has solid programs in the following areas:

- Reliability characterization
- Product performance characterization
- Pb-free assembly
- Halogen-free products
- Design for environment
- Advanced Packaging

Marshall Andrews, Executive Director of HDP User Group, said, "Our project agenda comes from our members, who are leaders in electronic product design and manufacturing. Our member's ideas and technical strength have kept our organization relevant over the years and enabled us to provide exceptional value to them through our infrastructure for collaboration."

As it enters its 21st year in business HDP User Group strives to continue its high level of return for its membership. The organization expects to grow its membership base while maintaining the



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rapid project progress members expect. With current projects involving Through Silicon Vias (TSV) and Optoelectronics, HDP is enhancing its portfolio of emerging technology projects and expects future, expanded activities in these areas.

About HDP User Group

HDP User Group (www.hdpug.org) a global research and development organization based in Cave Creek Arizona, is dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963